

WHAT IS CLAIMED IS:

1. A condenser microphone comprising:

a semiconductor device comprising: a conductive pattern;
a semiconductor element placed on the conductive pattern; and
5 a sealing resin for integrally sealing the conductive pattern
and the semiconductor element;

a fixed electrode layer electrically connected to the
semiconductor element and provided on the surface of the
sealing resin to form one electrode of a condenser; and

10 a vibration film provided to be opposed to the fixed
electrode layer to provide another electrode of the condenser.

2. The condenser microphone according to claim 1, wherein
the fixed electrode layer is formed on the surface of the sealing
resin opposing the face from which the conductive pattern is
15 exposed.

3. The condenser microphone according to claim 2, wherein
the fixed electrode layer is electrically connected via a
penetrated hole provided in the sealing resin to the conductive
pattern.

20 4. The condenser microphone according to claim 1, wherein
the fixed electrode layer consists of a plating film.

5. The condenser microphone according to claim 1, wherein
the sealing resin exposes the back face of the conductive pattern

and coats the semiconductor element and the conductive pattern.

6. The condenser microphone according to claim 1, wherein the semiconductor device, the fixed electrode layer, and the vibration film are stored in a case member and the semiconductor
5 device is fixed via a substrate to the inner wall of the case member.

7. The condenser microphone according to claim 1, wherein the semiconductor device, the fixed electrode layer, and the vibration film are stored in a case member and the semiconductor
10 device is directly fixed to the inner wall of the case member.

8. A condenser microphone comprising:
a semiconductor device comprising: a conductive pattern;
a semiconductor element placed on the conductive pattern; and
a sealing resin for integrally sealing the conductive pattern
15 and the semiconductor element;

a fixed electrode layer for forming one electrode of the condenser comprising a part of the conductive pattern; and

a vibration film that is provided to be opposed to the fixed electrode layer to provide another electrode of the
20 condenser.

9. The condenser microphone according to claim 8, wherein the conductive pattern to which the semiconductor element is fixed is used as the fixed electrode layer.

10. The condenser microphone according to claim 8, wherein the sealing resin exposes the back face of the conductive pattern and covers the semiconductor element and the conductive pattern.

11. The condenser microphone according to claim 8, wherein
5 the semiconductor device, the fixed electrode layer, and the vibration film are stored in a case member and the semiconductor device is fixed via a substrate to the inner wall of the case member.